

IME01-001

In the specification:

The last paragraph on P. 10 now reads as follows:

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A<sup>1</sup>

As seen in FIG. 3, arrow 33 (henceforth to be referred to as  $R_{Sub\_Z}$ ) represents the thermal resistance of the thermal path between balancing block 1 and the heat sink 3. Similarly, arrow 31 ( $R_{Chip\_Z}$ ) points to the thermal path between balancing block 1 and the chamber 6, arrow 34 ( $R_{Sub\_X}$ ) points to the thermal path between each pair of adjacent blocks 1 through the substrate 2, and arrow 32 ( $R_{Chip\_X}$ ) points to the thermal path between adjacent blocks 1 through chip 5. To obtain excellent thermal isolation between chambers 6,  $R_{Sub\_X}$  and  $R_{Chip\_X}$  should be much larger than  $R_{Sub\_Z}$ . An approximate relation can be stated as follows:

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In the claims:

✓  
Please cancel claim 26.

Please amend the following claims:

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- A<sup>2</sup>
1. An apparatus for simultaneously performing multiple, independently controlled, chemical reactions, comprising:  
a printed circuit board mounted on a heat sink;